

ABSTRACT

A device-incorporated substrate and a method of manufacturing a device-incorporated substrate, as well as a printed circuit board and a method of manufacturing a printed circuit board in which a fine-pitch conductor pattern can be formed on an insulating layer with high precision while securing the dimensional stability of the conductor pattern, are provided. A transfer sheet (61) has a structure that includes two layers, a metal base material (62) and a dissolvee metal layer (64), and a conductor pattern (55) is formed on the dissolvee metal layer (64) through electroplating. Then, after the transfer sheet (61) on which the conductor pattern (55) is formed is adhered onto an insulating base material (51), the transfer sheet (61) is removed through a step of separating the metal base material (62) from the dissolvee metal layer (64), and a step of selectively dissolving and removing the dissolvee metal layer (64) with respect to the conductor pattern (55).